


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/24/14375	
1.3 Title of PCN	AMKOR ATP (Philippines) TFBGA package copper palladium bonding wire introduction on STM32F4x, STM32F7x, STM32G4x and STM32H7x listed products.	
1.4 Product Category	STM32F42/F43x, STM32F46/F47x STM32F74x, STM32F75/F76/F77x, STM32G47/G48x, STM32H72/H73x, STM32H74/H75x and STM32H7A/H7Bx	
1.5 Issue date	2024-10-04	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	AMKOR ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - MUAR (Malaysia) gold wire - ASE Kaohsiung (Taiwan) Gold or CuPd wire - AMKOR ATP (Philippines) gold wire	Current Wire bonding material: - MUAR (Malaysia) gold wire - ASE Kaohsiung (Taiwan) Gold or CuPd wire - AMKOR ATP (Philippines) gold wire New Wire bonding material : - AMKOR ATP (Philippines) copper palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
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7. Timing / schedule

7.1 Date of qualification results	2024-12-16
7.2 Intended start of delivery	2025-02-17
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	14375 MDRF-GPM-RER2418 PCN14375 ATP3 TFBGA CuPd wire - products reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-10-04

9. Attachments (additional documentations)	
14375 Public product.pdf 14375 MDRF-GPM-RER2418 PCN14375 ATP3 TFBGA CuPd wire - products reliability plan.pdf 14375 PCN14375_Additional information.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F429NIH6	
	STM32F746NGH6	
	STM32F769NIH6	
	STM32H745XIH3	
	STM32H745XIH3TR	

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